

CONTENTS

Preface	7
Introduction	7
Chapter 1. Basic Processes of IC Manufacture	13
1.1. Diffusion	13
1.2. Epitaxy	16
1.3. Oxidation	17
1.4. Photolithography	18
1.5. Thin Film Deposition	19
Chapter 2. Monolithic Integrated Circuits	24
2.1. Steps of IC Manufacture	24
2.2. Isolation of Circuit Elements	28
2.3. Transistors	31
2.4. Diodes	38
2.5. Resistors	42
2.6. Capacitors	48
2.7. Metallization	51
2.8. Elements of Metal-Oxide-Semiconductor (MOS) Integrated Circuits	53
2.9. Principles of MOS IC Manufacture	58
2.10. Charge-Coupled Devices	63
2.11. Topology of Monolithic ICs	67
Chapter 3. Hybrid Integrated Circuits	70
3.1. Principles of Manufacture	70
3.2. Substrates	73
3.3. Conductors and Contact Pads	74
3.4. Thin-Film Resistors	76
3.5. Thin-Film Capacitors	79
3.6. Thin-Film RC Elements	82
3.7. Thin-Film Inductors	82
3.8. Thick-Film Hybrid ICs	83
3.9. Thick-Film Elements	85
3.10. Hybrid IC Elements	89
3.11. Hybrid IC Layout Design	91
3.12. Compatible Integrated Circuits	94
Chapter 4. Assembly of Integrated Circuits. Typical Circuit Packages	97
4.1. Semiconductor IC Assembly	97
4.2. Assembly of Hybrid Integrated Circuits	102
Chapter 5. Digital Integrated Circuits	106
5.1. Logic Elements	106
5.2. Direct-Coupled Transistor Logic and Its Versions	111
5.3. Diode Transistor Logic	116
5.4. Transistor Transistor Logic	119
5.5. Emitter-Coupled Logic	124

5.6. Integrated Injection Logic	127
5.7. IC MOS Logic	129
5.8. Medium-Scale Integration	134
Chapter 6. Analog Integrated Circuits	146
6.1. General	146
6.2. Differential Amplifier	147
6.3. Narrow-Band Amplifiers	149
6.4. Audio-Frequency Amplifiers	150
6.5. Operational Amplifiers	152
Chapter 7. Large Scale Integration Circuits	156
7.1. General	156
7.2. Metallization	156
7.3. LSI Circuitry and Technology	157
7.4. LSI Design and Fabrication	161
7.5. LSI Circuits as Functional Blocks	165
Chapter 8. Microprocessors	167
8.1. General	167
8.2. Microprocessor Organization	168
8.3. Trends in Microprocessor Technology	172
8.4. Microprocessor Generations	173
8.5. Microprocessor Set Series K589	182
Chapter 9. LSI Memories	192
9.1. Classification and Parameters of Memories	192
9.2. Semiconductor Memory Organization	194
9.3. Random Access Memories	196
9.4. Serial Access Memories (SAM)	208
9.5. Semiconductor Read-Only Memories (ROMs)	211
Chapter 10. Functional Microelectronics	214
10.1. Trends in Microelectronics	214
10.2. Four-Layer Functional Devices	215
10.3. Delay Lines and Rectifiers	216
10.4. Molelectronics	218
10.5. Optoelectronics	218
10.6. Acoustoelectronics	219
10.7. Cryoelectronics	221
10.8. Thermoelectronics	222
Chapter 11. Reliability and Testing	222
11.1. Reliability of Microcircuits	223
11.2. Testing	226
11.3. Conclusion	232
Appendix	237
Index	239